

FOR HIGH PERFORMANCE TIM APPLICATIONS

IceKap™ P30000 is a silicone-free, high-performance thermal interface material designed for use in TIM 1.5 and TIM 2 applications. In certain instances, IceKap™ P30000 can be used in TIM 1 applications

IceKap™ P30000 utilizes a unique polymer chosen to maximize system performance. The specially designed polymer package:

- Minimizes contact thermal resistance at the interface while offering high thermal conductivity
- Minimizes migration (pump out) at CPU operating temperatures
- Provides “joint healing” capabilities (improved device reliability)
- Contains no silicone
- Allows easy rework, requiring minimal force to separate components
- Survives multiple solder reflow operations

IceKap™ P30000 can be pre-applied to components and stored for future shipment to device assemblers.

FEATURES AND BENEFITS

- Very high thermal performance
- Minimal pump out
- High reliability
- Silicone-free
- Joint healing
- Easy rework
- Solder re-flow compatible

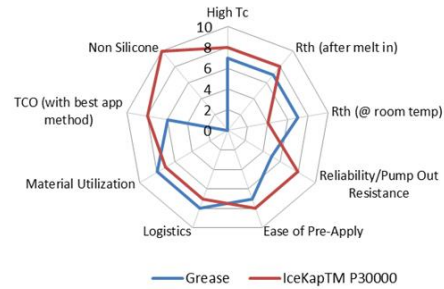
MARKETS / APPLICATIONS

- Semiconductor Packaging
- Graphics Card
- Notebooks
- Desktops
- Servers
- IGBTs
- Automotive
- Memory Modules
- Game Consoles
- Set Top Boxes

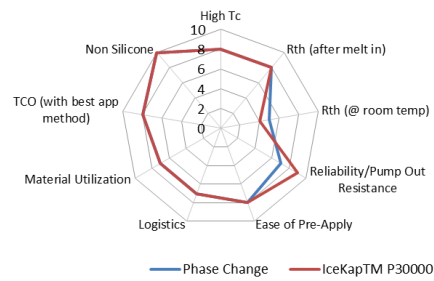
TYPICAL PROPERTIES

TYPICAL PROPERTY	TEST METHOD	
	IceKap™ P30000	
Color	Grey	Visual
Specific Gravity (g/cc)	2.5	Helium Pycnometer
Softening Temperature (°C)	80 - 120	
Minimum BLT (microns)	25	Maximum Filler Particle Size
Minimum BLT - Recommended (microns)	50	
Max Continuous Use Temp (°C)	125	Laird Reliability Test Methods
Thermal Conductivity (W/mK)	5.5	Hot Disk Thermal Constants Analyzer
Thermal Resistance		
cm ² °C/W	0.148	ASTM D5470 at 10 psi & 70°C
in ² °C/W	0.023	
Solder Reflow Profile	Min 3x	IPC/JEDEC J-STD-020D.1
UL Flammability	V-0 (in progress)	UL 94
Thickness (microns)	125, 200, 250	

VALUE PROPOSITION (as compared to Thermal Grease)



VALUE PROPOSITION (as compared to Thermal Phase Change)



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